

# SOT1944-1

VFBGA100, very thin fine-pitch ball grid array package, 100 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

7 May 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	VFBGA100
<b>Package style descriptive code</b>	VFBGA (very thin fine-pitch ball grid array)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	3-4-2018
<b>Manufacturer package code</b>	98ASA01134D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	6	-	mm
E	package width	-	-	6	-	mm
A <sub>2</sub>	package height	-	-	0.8	-	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	100	-	A/A



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## 2. Package outline

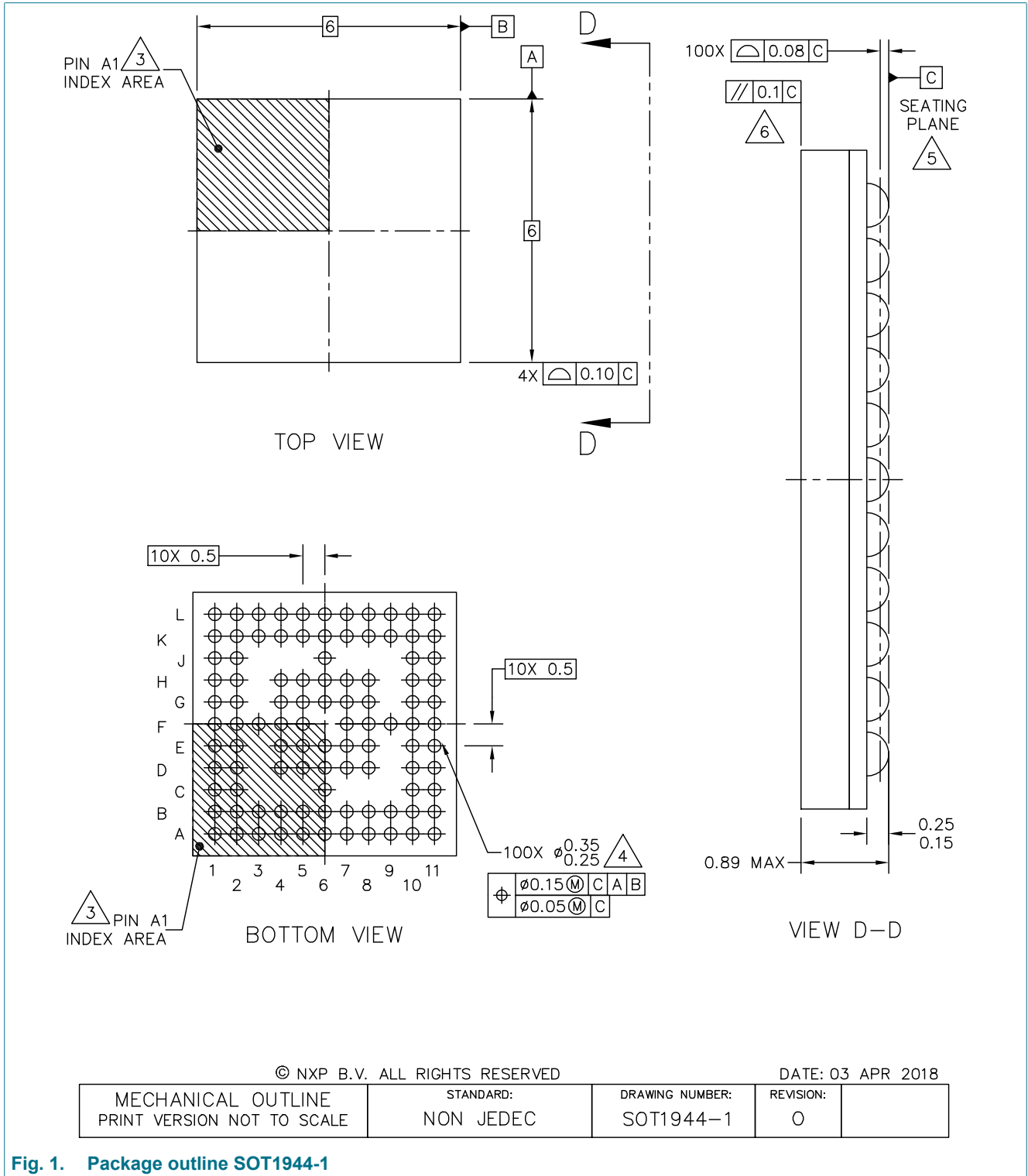


Fig. 1. Package outline SOT1944-1

VFBGA100, very thin fine-pitch ball grid array package, 100 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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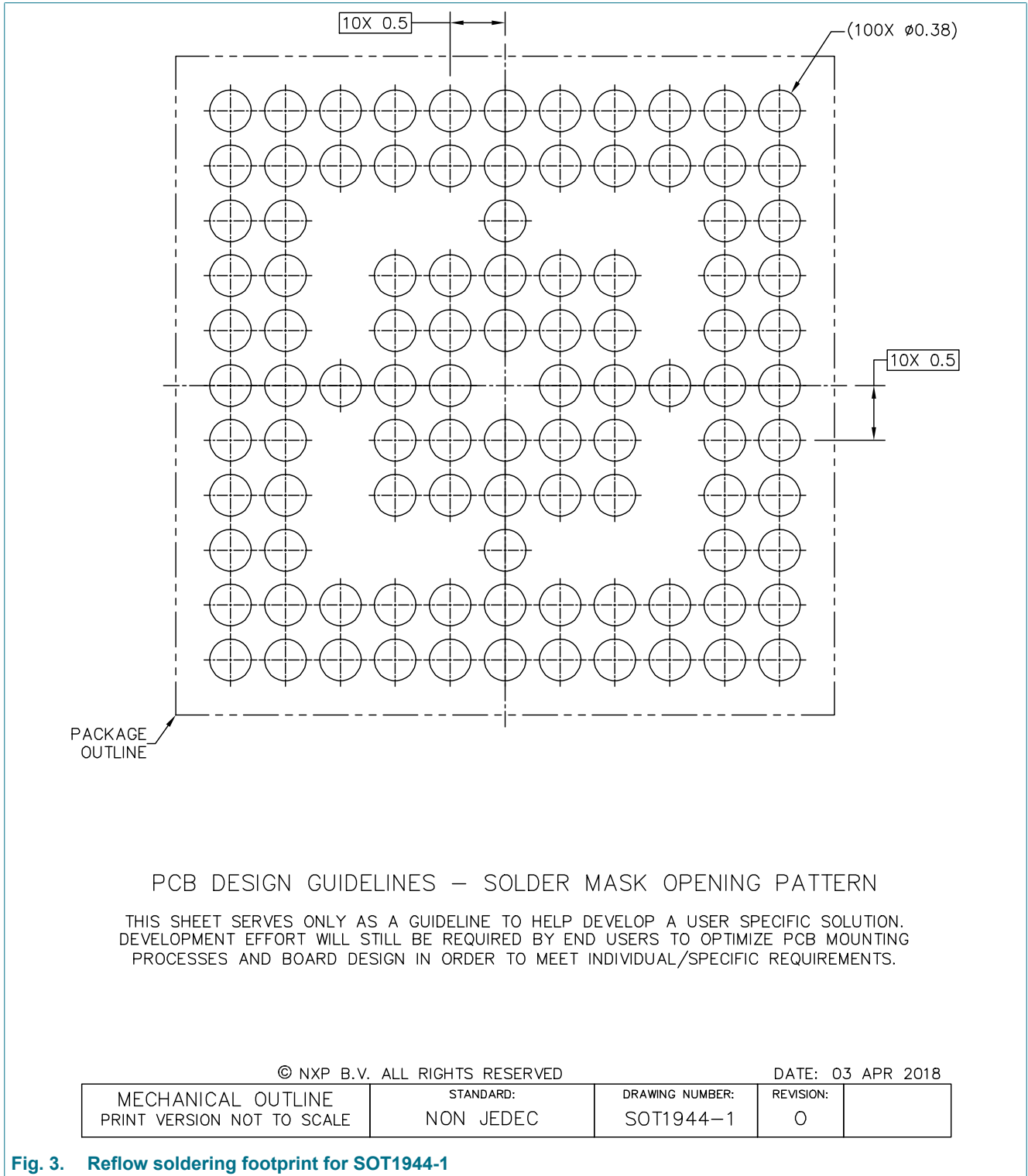
DATE: 03 APR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1944-1	REVISION: 0	
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Fig. 2. Package outline note VFBGA100 (SOT1944-1)

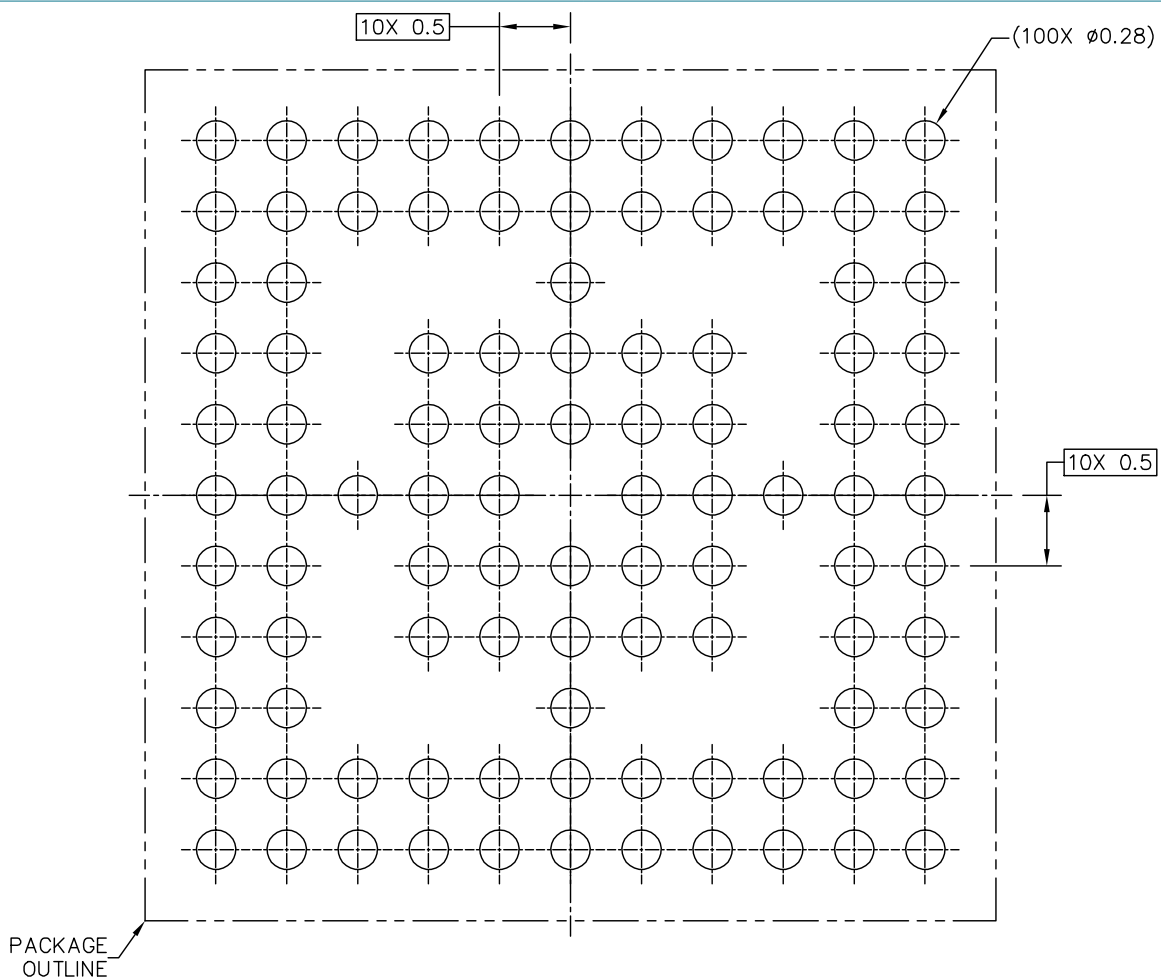
VFBGA100, very thin fine-pitch ball grid array package, 100 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

### 3. Soldering



**Fig. 3. Reflow soldering footprint for SOT1944-1**

VFBGA100, very thin fine-pitch ball grid array package, 100 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body



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Fig. 4. Reflow soldering footprint part2 for VFBGA100 (SOT1944-1)

VFBGA100, very thin fine-pitch ball grid array package, 100 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

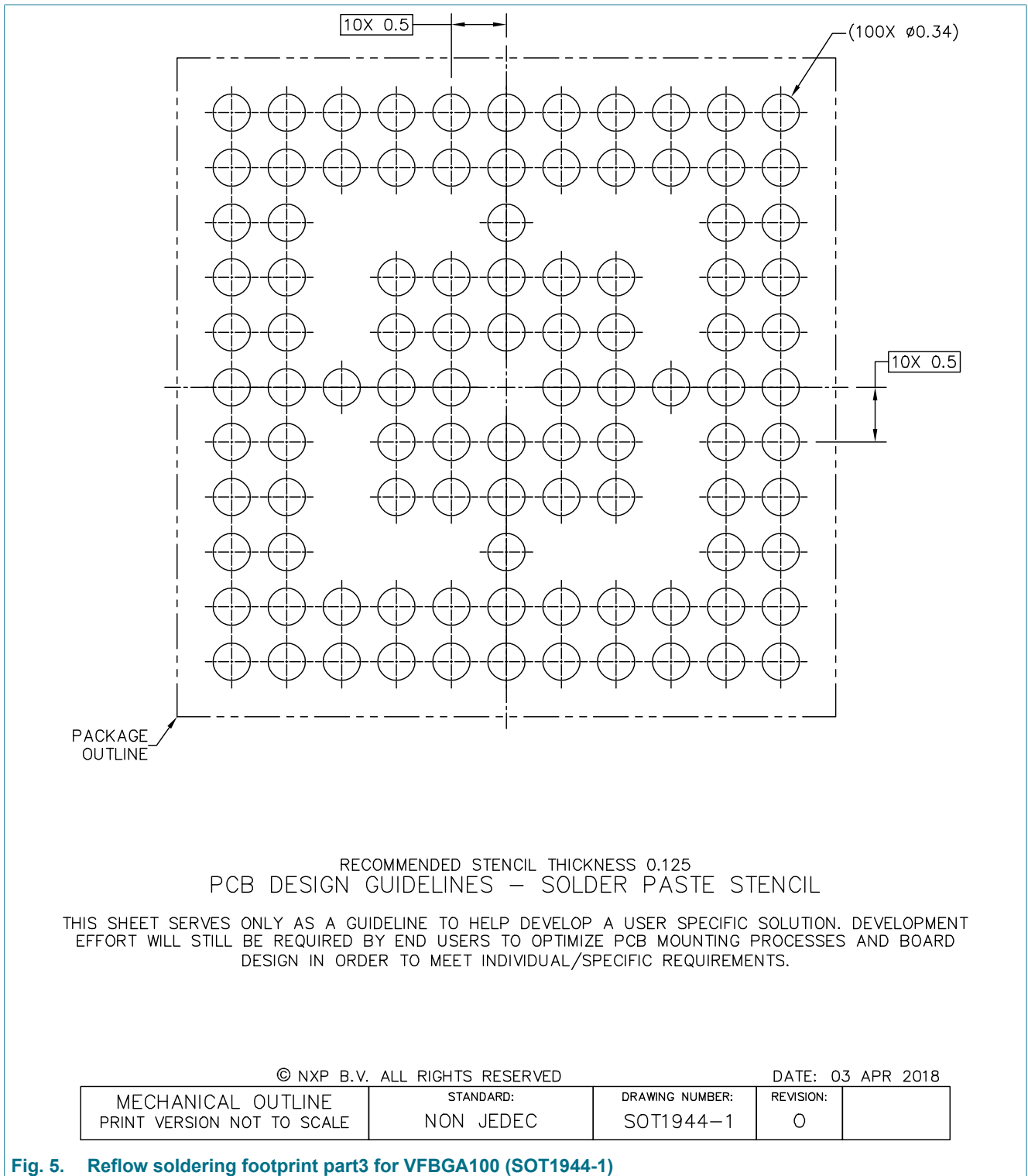


Fig. 5. Reflow soldering footprint part3 for VFBGA100 (SOT1944-1)

VFBGA100, very thin fine-pitch ball grid array package, 100 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

## 4. Legal information

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